SSL1208 SERIES

1. PART NO. EXPRESSION:

SSL1005-R21MF

(a) Series code

(d) Tolerance code : M = ±20%

(a) (b)

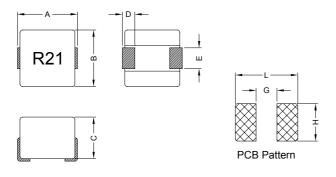
(c) (d)(e)

(b) Dimension code

(c) Inductance code : R21 = 0.21uH

(e) F: Lead Free

2. CONFIGURATION & DIMENSIONS:



Unit:m/m

Α	В	С	D	E	G	Н	L	
13.46 Max.	12.95 Max.	8.0 Max.	2.54±0.5	5.0±0.5	7.1 Max.	7.6 Max.	13.8 Max.	

3. SCHEMATIC:



4. GENERAL SPECIFICATION:

a) Operating temp. : -55°C to +125°C

b) Storage temp. : -55°C to +125°C

c) Irms (A) : Will cause coil temp. to rise approximately $\Delta T = 40\,^{\circ}\text{C}$ without core loss.

d) Isat (A) : Will cause L0 to drop approximately 20%

e) Part temperature (ambient + temp. rise): Should not exceed 125°C under worst case operating conditions.

5. ELECTRICAL CHARACTERISTICS:

Part No.	Inductance Lo(uH)	Test Freq. (Hz)	DCR (mΩ) Max.	Irms (A) Max.	Isat (A) Max.
SSL1208-R15YF	0.15 ±30%	0.1V/500K	0.60	50	55
SSL1208-R21MF	0.21 ±20%	0.1V/500K	0.60	45	50
SSL1208-R26MF	0.26 ±20%	0.1V/500K	0.60	40	45
SSL1208-R32MF	0.32 ±20%	0.1V/500K	0.60	40	41
SSL1208-R44MF	0.44 ±20%	0.1V/500K	0.60	28	30

Pb

RoHS Compliant

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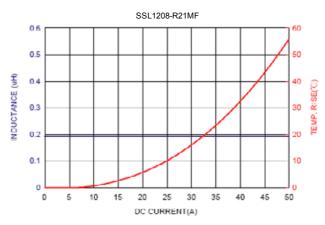


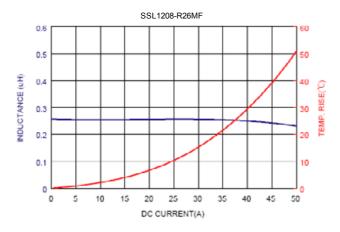
PG. 1

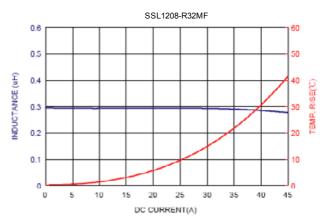
SSL1208 SERIES

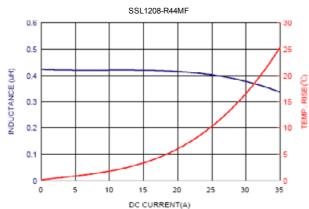
6. CHARACTERISTICS CURVES:













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PG. 2

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7. RELIABILITY AND TEST CONDITION:

ITEM	PERFORMANCE	TEST CONDITION		
Electrical Characteristics 7	Test			
Inductance	Refer to standard electrical characteristics list	HP4284A, CH11025, CH3302, CH1320, CH1320S LCR meter.		
DCR		CH16502, Agilent33420A Micro-Ohm Meter.		
Heat Rated Current (Irms)		Irms(A) will cause the coil temperature rise approximately ΔT=40°C without core loss 1. Applied the allowed DC current 2. Temperature measured by digital surface thermometer		
Saturation Current (Isat)		Isat(A) will cause Lo to drop approximately 20%		
Mechanical Performance	Test			
Solderability Test	More than 90% of the terminal electrode should be covered with solder. Preheating Dipping Natural cooling 150°C 150°C 4±1 seconds	Preheat: 150°C, 60sec. Solder: Sn-Ag3.0-Cu0.5 Solder Temperature: 230±5°C Flux for lead free: rosin Dip Time: 4±1sec.		
Solder Heat Resistance	Preheat : 150°C, 60sec. 2. Inductance change : Within ±20% 2. Inductance change : Within ±20% Preheating Dipping Natural cooling Preheating Dipping Natural cooling Dipping Natural cooling Dipping Natural cooling Dip Time : 10±0.5sec.			
Reliability Test				
High Temperature Life Test		Temperature : 125±5°C Time : 500±12 hours Measure at room temperature after placing for 2 to 3 hrs.		
Low Temperature Life Test	Appearance : No damage Inductance : Within ±20% of initial value.	Temperature : -55±5°C Time : 500±12 hours Measure at room temperature after placing for 2 to 3 hrs.		
Thermal Shock	No disconnection or short circuit.	Conditions of 1 cycle. Step Temperature (°C) Times (min.) 1 -55±3 30±3 2 Room Temperature Within 3 3 +125±3 30±3 4 Room Temperature Within 3 Total: 5 cycles Measure at room temperature after placing for 2 to 3 hrs		
Humidity Resistance	Appearance : No damage Inductance : Within ±20% of initial value. No disconnection or short circuit.	Temperature: 40±5°C Humidity: 90% to 95% Applied Current: Rated Curent Time: 500±12 hours Measure at room temperature after placing for 2 to 3 hrs.		



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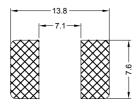
PG. 3



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8. SOLDERIND AND MOUNTING:

8-1. Recommended PC Board Pattern (Unit: mm)



8-2. Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. Our terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

8-2.1 Solder Re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

8-2.2 Soldering Iron (Figure 2):

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Note:

- a) Preheat circuit and products to 150°C.
- b) 280°C tip temperature (max)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (max)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 3 secs.

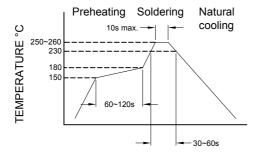


Figure 1. Re-flow Soldering

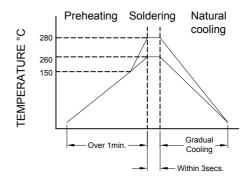


Figure 2. Iron Soldering



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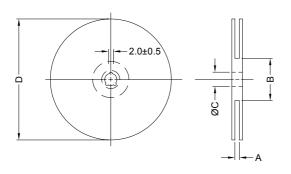
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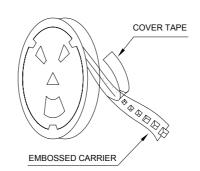


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9. PACKAGING INFORMATION:

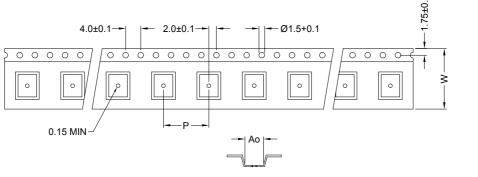
9-1. Reel Dimension





Туре	A(mm)	B(mm)	C(mm)	D(mm)
13" x 24mm	24.0±0.5	75±2	13.5±0.5	330

9-2 Tape Dimension



t-
B B
Ko

Series	Ao(mm)	Bo(mm)	Ko(mm)	P(mm)	W(mm)	t(mm)
SSL1208	13.05±0.1	13.05±0.1	8.2±0.1	16.0±0.1	24.0±0.3	0.35±0.05

9-3 Packaging Quantity

Size	SSL1208
Chip / Reel	400
Inner Box	1200
Carton	2400

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